

## HT5010

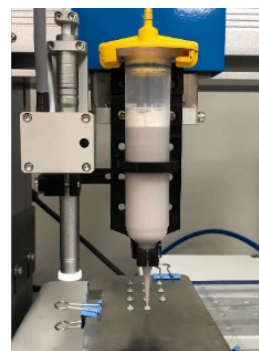
### Thermally Conductive Gap Fillers

#### BENEFITS AND FEATURES

- High thermal performance
- Low contact resistance
- Easily dispensable and reworkable
- High compressibility for low stress applications
- Reliable thermal performance
- Anti-crack and dripping
- Anti-blocking and abrasion

#### OVERVIEW

Honeywell HT5010 one-part Gap Filler provides an effective thermal properties and high conformability with its high compressibility. It is formulated to deliver high dispense rates for improved productivity, long-term reliability performance and easy reworkable. It is designed to minimize thermal resistance at interfaces, maintain excellent performance through reliability testing.



#### TYPICAL APPLICATIONS

- Consumer electronics
- Telecommunications equipment
- Automotive electronics
- Power supplies & semiconductors
- Memory & power modules
- Power electronics

#### STORAGE & USE

Shelf Life 12 months at 0-35°C, <65%RH

Property	HT5010	Test Method
Feature	Silicone-based	-
	Pre-cured	-
Thermal Conductivity (W/m·K)(1mm@10spi)	5.0	ASTM D5470
Thermal Impedance (K.In <sup>2</sup> /W)	0.28	ASTM D5470 @1mm 10psi
Minimum BLT(mm)	0.14	-
Dispense Rate (g/min)	>14	30cc EFD syringe/ no tip/ 0.100" orifice/ @0.6Mpa
Specific Gravity	3.4	ASTM D792
Dielectric Strength (KV/mm)	8	ASTM D149
Out Gassing (TML)	<0.05%	ASTM E595
Color	Grey	Visual
Flammability Rating	V-0	UL 94

#### Honeywell Electronic Materials

USA: 1-509-252-2102  
 Mainland China: 400-840-2233  
 Germany: 49-5137-999-9199  
 Japan: 81-3-6730-7092  
 Korea: 82-2-3483-5076  
 Singapore: 65-6580-3593  
 Taiwan: 886-3-6580300 ext.312

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